

0039-7632-0X



#15/C
4/11/02
"RESPONSE UNDER 37 CFR 1.116-
EXPEDITED PROCEDURE EXAMINING
GROUP 1765"

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

HIROYUKI YANO ET AL

: GROUP ART UNIT: 1765

SERIAL NO. 09/531,163

:

FILED: MARCH 17, 2000

: EXAMINER: DEO, D.

FOR: AQUEOUS DISPERSION, AQUEOUS
DISPERSION FOR CHEMICAL
MECHANICAL POLISHING USED
FOR MANUFACTURE OF SEMI-
CONDUCTOR DEVICES, METHOD
FOR MANUFACTURE OF ...

AMENDMENT AND REQUEST FOR RECONSIDERATION

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Responsive to the Advisory Action of March 15, 2002, Applicants respectfully
request reconsideration of the above-identified application in view of the following
amendment and remarks.

IN THE CLAIMS

Please amend the claims as shown in the marked-up copy following this amendment
to read as follows.

44. (Amended) An aqueous dispersion for chemical mechanical polishing used in the
manufacture of semiconductor devices, said dispersion comprising polymer particles,
inorganic particles and water, wherein the zeta potential of said polymer particles and the zeta

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